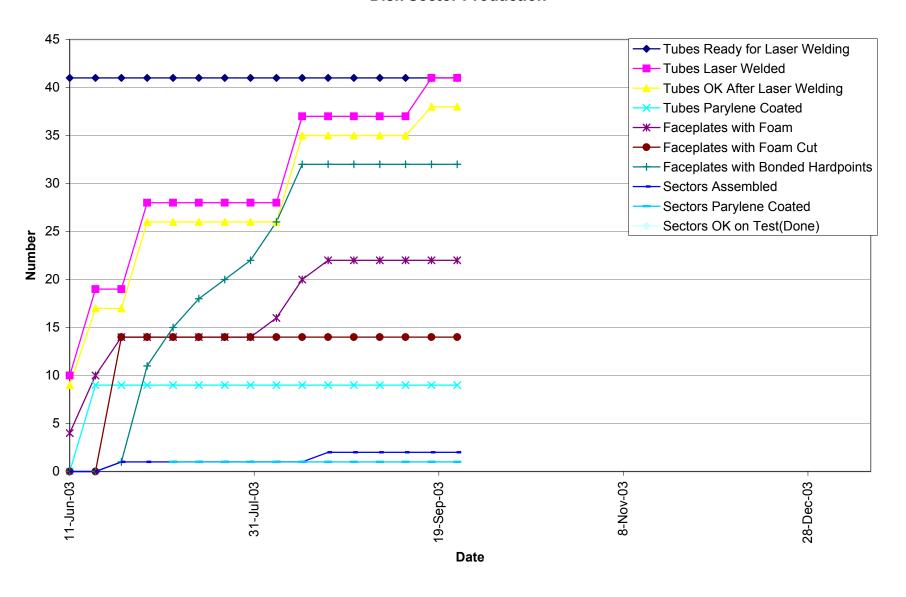
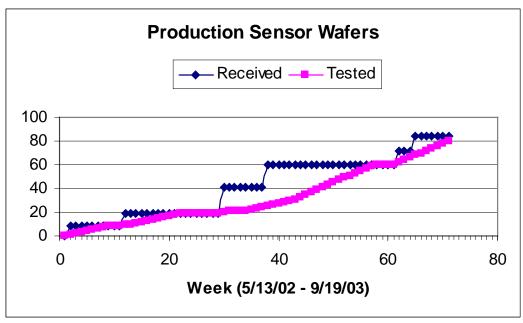
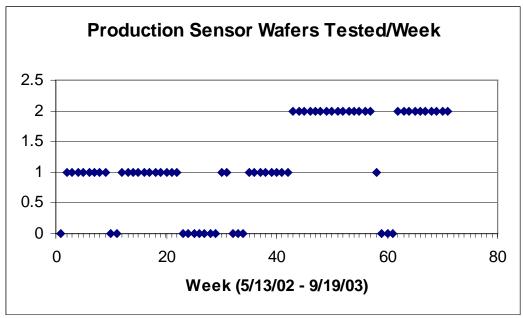
Disk Sector Production

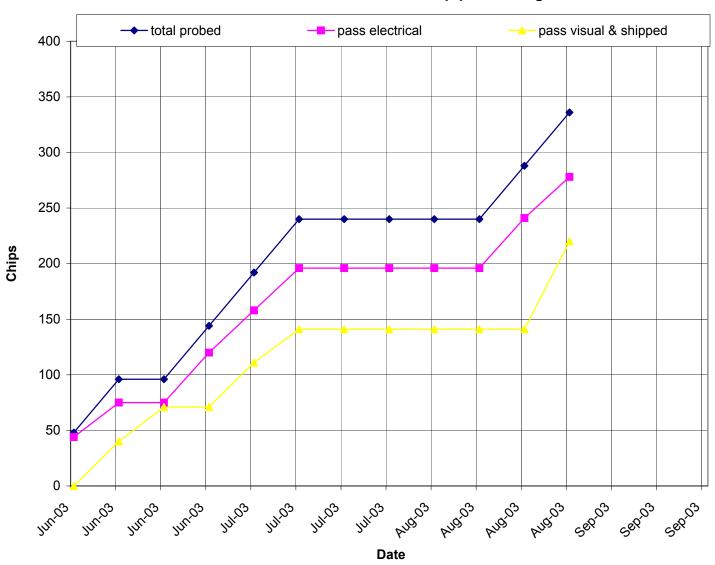


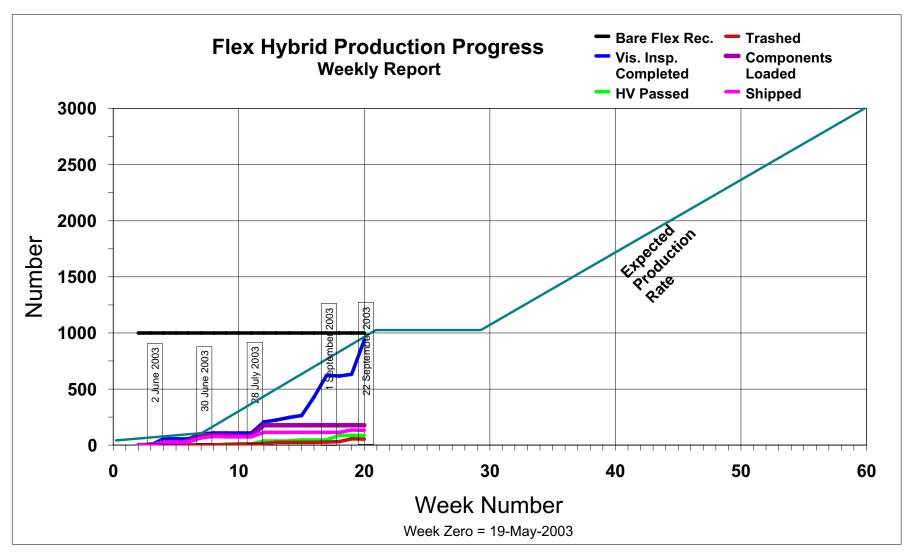
University Of New Mexico ATLAS Sensor Wafer Production Measurement Status





Production chip processing





Notes

Assembly sequence: Visual Inspection -> Component Loading -> HV Test -> MCC Attachment & Wire Bonding -> ready for Pitail Attachment and Module Construction Visual Inspection Completed refers to flex that are ready for component loading.

HV Tested refers to flex hybrids that are ready for MCC attachment.

Flex+MCC will be shown in a seperate chart when MCC delivery rates are known.

The above data includes only flex hybrids that are considered good.

Trashed includes bad flex + flex that have been sacrificed for developmental purposes. Data is cumulative.

LBL Moudule FV5 Assembly

